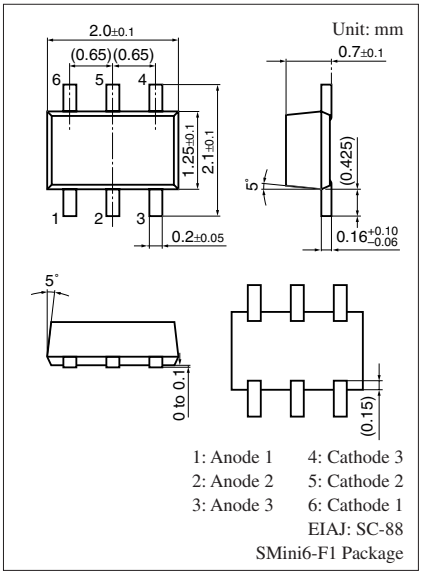
MA6J784

Silicon epitaxial planar type

For super high speed switching
For small current rectification

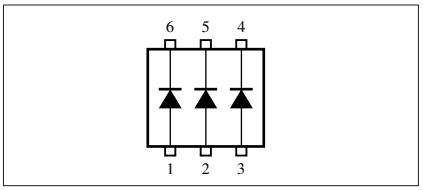
■ Features

- $I_{F(AV)}$ = 100 mA rectification is possible
- Optimum for high frequency rectification because of its short reverse recovery time (t_{rr})
- Low forward voltage V_F and good rectification efficiency



Marking Symbol: M8A

Internal Connection



■ Absolute Maximum Ratings T_a = 25°C

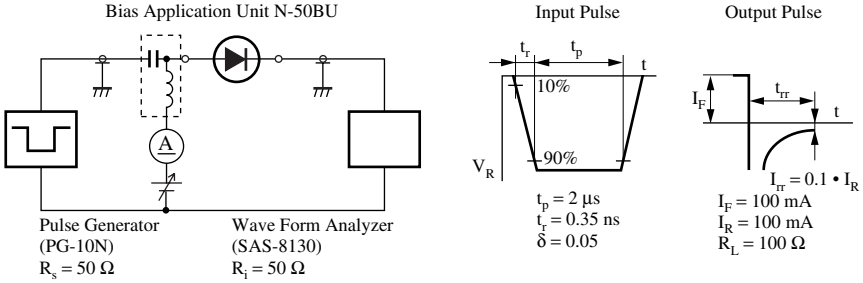
Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	30	V
Repetitive peak reverse voltage	V_{RRM}	30	V
Average forward current *2	$I_{F(AV)}$	100	mA
Peak forward current *2	I_{FM}	300	mA
Non-repetitive peak forward surge current *1, 2	I_{FSM}	1	A
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	−55 to +125	°C

Note) ∗1: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)
∗2: Value of each diode in double diodes used.

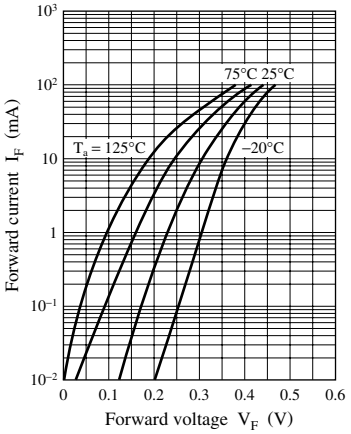
■ Electrical Characteristics T_a = 25°C ± 3°C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	I_F = 100 mA			0.55	V
Reverse current	I_R	V_R = 30 V			15	µA
Terminal capacitance	C_t	V_R = 0 V, f = 1 MHz		20		pF
Reverse recovery time *	t_{rr}	$I_F = I_R$ = 100 mA I_{rr} = 0.1 • I_R , R_L = 100 Ω		2.0		ns

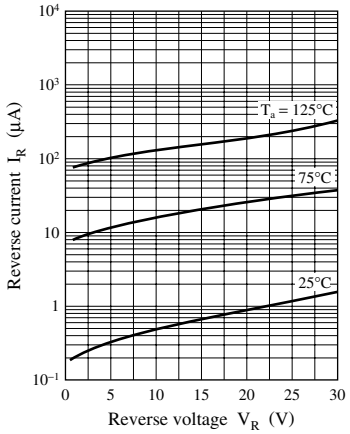
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. Rated input/output frequency: 250 MHz
4. ∗: t_{rr} measuring instrument



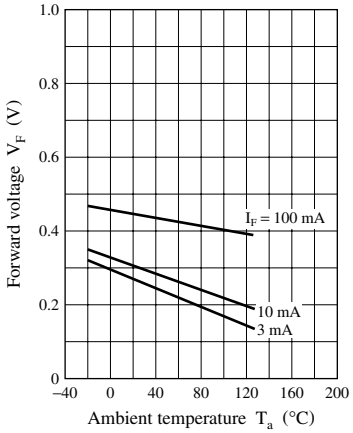
I_F — V_F



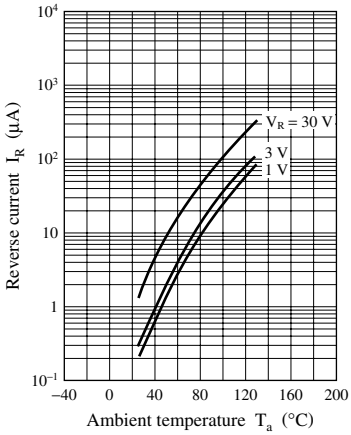
I_R — V_R



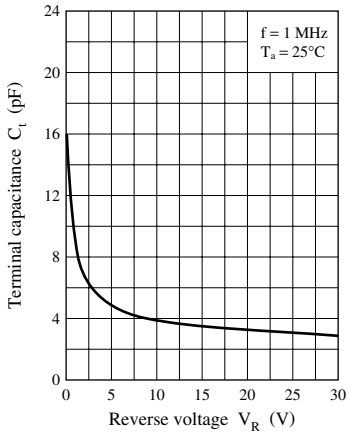
V_F — T_a



I_R — T_a



C_t — V_R



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